

Customer No.: 31561
Application No.: 10/604,650
Docket No.: 9246-US-PA

AMENDMENT

Please amend the application as indicated hereafter.

In the Claims :

- 1. (original) A substrate, comprising:
a dielectric structure;
an interconnection structure interlacing inside the dielectric structure;
and
a solder mask covering the dielectric structure, wherein the solder mask
has a coefficient of thermal expansion substantially equal to the dielectric structure
contacting the solder mask.**
- 2. (original) The substrate according to claim 1, wherein the material of
the solder mask is epoxy resin.**
- 3. (original) The substrate according to claim 1, wherein the material of
the solder mask is bismaleimide-triazine.**
- 4. (original) The substrate according to claim 1, wherein the solder mask
further covers the interconnection structure, the solder mask having at least one
opening to expose the interconnection structure.**
- 5. (original) The substrate according to claim 1, wherein the solder mask
has the same material as the dielectric structure contacting the solder mask.**
- 6. (original) A substrate, comprising:**

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6. (original) A substrate, comprising:

a dielectric structure;

an interconnection structure interlacing inside the dielectric structure;

and

a solder mask covering the dielectric structure, wherein the glass transition temperature of the material used for manufacturing the solder mask is over 200 degree C.

7. (original) The substrate according to claim 6, wherein the solder mask further covers the interconnection structure, the solder mask having at least one opening to expose the interconnection structure.

8. (original) The substrate according to claim 6, wherein the material of the solder mask is epoxy resin.

9. (original) The substrate according to claim 6, wherein the material of the solder mask is bismaleimide-triazine.

10.-25. (cancelled)